



FEATURES

Current output ranges: 0 mA to 24 mA or 4 mA to 20 mA
 ±0.03% FSR typical total unadjusted error (TUE)
 ±5 ppm/°C typical output drift
 2% overrange

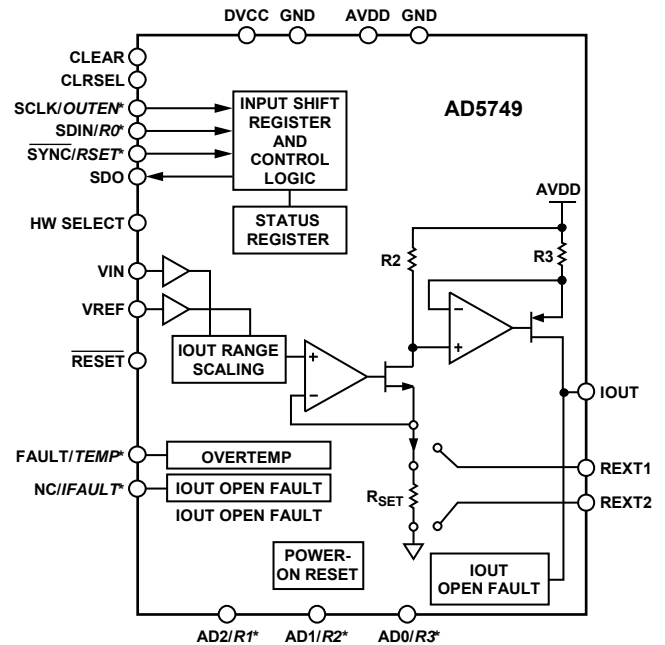
Flexible serial digital interface
 On-chip output fault detection
 PEC error checking
 Asynchronous CLEAR function
 Power supply range

AV_{DD}: 12 V (± 10%) to 55 V (maximum)
 Output loop compliance to AV_{DD} – 2.75 V
 Temperature range: –40°C to +105°C
 32-lead, 5 mm × 5 mm LFCSP package

APPLICATIONS

Process control
 Actuator control
 PLCs

FUNCTIONAL BLOCK DIAGRAM



*DENOTES SHARED PIN. SOFTWARE MODE DENOTED BY REGULAR TEXT, HARDWARE MODE DENOTED BY *ITALIC* TEXT. FOR EXAMPLE, FOR FAULT/TEMP* PIN, IN SOFTWARE MODE, THIS PIN TAKES ON FAULT FUNCTION. IN HARDWARE MODE, THIS PIN TAKES ON TEMP FUNCTION.

Figure 1.

GENERAL DESCRIPTION

The AD5749 is a single channel, low cost, precision, current output driver with hardware or software programmable output ranges. The software ranges are configured via an SPI-/MICROWIRE™-compatible serial interface. The AD5749 targets applications in PLC and industrial process control. The analog input to the AD5749 is provided from a low voltage, single-supply digital-to-analog converter (DAC) and is internally conditioned to provide the desired output current/voltage range.

The output current range is programmable across two current ranges: 0 mA to 24 mA, or 4 mA to 20 mA. Current output is open-circuit protected and can drive inductive loads of 0.1 H. The device is specified to operate with a power supply range from 10.8 V to 55 V. Output loop compliance is 0 V to AV_{DD} – 2.75 V.

The flexible serial interface is SPI and MICROWIRE compatible and can be operated in 3-wire mode to minimize the digital isolation required in isolated applications. The interface also features an optional PEC error checking feature using CRC-8

error checking, useful in industrial environments where data communication corruption can occur.

The device also includes a power-on reset function ensuring that the device powers up in a known state and an asynchronous CLEAR pin that sets the outputs to the low end of the selected current range.

An HW SELECT pin is used to configure the part for hardware or software mode on power-up.

Table 1. Related Devices

Part No.	Description
AD5750	Industrial current/voltage output (I/V) driver with programmable ranges
AD5751	Industrial I/V output driver, single-supply, 55 V maximum supply, programmable ranges
AD5748	Industrial I/V output driver with programmable ranges
AD5410/ AD5420	Single-channel, 12-/16-bit, serial input, current source output DAC
AD5412/ AD5422	Single-channel, 12-/16-bit, serial input, I/V output DAC

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REVISION HISTORY

9/2020—Rev. D to Rev. E

Changed CP-32-2 to CP-32-7.....	Throughout
Changes to Figure 4.....	8
Updates Outline Dimensions.....	26
Changes to Ordering Guide	26

1/2018—Rev. C to Rev. D

Changed CP-32-7 to CP-32-2.....	Throughout
Changes to Figure 1.....	1
Changed FAULT, IFAULT, TEMP, VFAULT Parameter to FAULT, IFAULT, TEMP Parameter; Table 2	4
Changes to Figure 4 and Table 5.....	8
Updates Outline Dimensions.....	26
Changes to Ordering Guide	26

3/2017—Rev. B to Rev. C

Changed CP-32-2 to CP-32-7.....	Throughout
Changes to Figure 4.....	8
Changes to Theory of Operation Section.....	16
Updated Outline Dimensions	26
Changes to Ordering Guide	26

10/2013—Rev. A to Rev. B

Changes to Table 4.....	7
Changes to Thermal Considerations Section and Table 12	24
Updated Outline Dimensions	26

7/2012—Rev. 0 to Rev. A

Changes to Figure 3.....	6
Changes to Status Bit Read Operation Section.....	21
Updated Outline Dimensions	26

7/2010—Revision 0: Initial Version

SPECIFICATIONS

$V_{DD} = 12\text{ V} (\pm 10\%)$ to 55 V (maximum), $DV_{CC} = 2.7\text{ V}$ to 5.5 V , $GND = 0\text{ V}$. $R_{LOAD} = 300\ \Omega$. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 2.

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
INPUT VOLTAGE RANGE		0 to 4.096		V	Output unloaded
Input Leakage Current	-1		+1	μA	
REFERENCE INPUT		4.096		V	External reference must be exactly as stated; otherwise, accuracy errors show up as error in output
Input Leakage Current	-1		+1	μA	
CURRENT OUTPUT					
Output Current Ranges	0		24	mA	
	4		20	mA	
Output Current Overranges ²	0		24.5	mA	See Detailed Description of Features section
	3.92		20.4	mA	See Detailed Description of Features section
ACCURACY (INTERNAL R_{SET})					
Total Unadjusted Error (TUE)					
A Version ²	-0.5		+0.5	% FSR	$T_A = 25^\circ\text{C}$
Relative Accuracy (INL)	-0.3	± 0.15	+0.3	% FSR	
Offset Error	-0.02	± 0.01	+0.02	% FSR	
Offset Error TC^2	-16		+16	μA	$T_A = 25^\circ\text{C}$
Dead Band on Output, RTI	-10	+5	+10	μA	
Gain Error		± 3		ppm FSR/ $^\circ\text{C}$	
Gain Error		8	14	mV	Referred to 4.096 V input range
Gain Error	-0.2		+0.2	% FSR	
Gain TC^2	-0.125	± 0.02	+0.125	% FSR	$T_A = 25^\circ\text{C}$
Full-Scale Error		± 10		ppm FSR/ $^\circ\text{C}$	
Full-Scale Error	-0.2		+0.2	% FSR	
Full-Scale TC^2	-0.125	± 0.02	+0.125	% FSR	$T_A = 25^\circ\text{C}$
Full-Scale TC^2		± 4		ppm FSR/ $^\circ\text{C}$	
ACCURACY (EXTERNAL R_{SET})					
Total Unadjusted Error (TUE)					
A Version ²	-0.3		+0.3	% FSR	$T_A = 25^\circ\text{C}$
Relative Accuracy (INL)	-0.1	± 0.02	+0.1	% FSR	
Offset Error	-0.02	± 0.01	+0.02	% FSR	
Offset Error	-14		+14	μA	$T_A = 25^\circ\text{C}$
Offset Error TC^2	-11	+5	+11	μA	
Dead Band on Output, RTI		± 2		ppm FSR/ $^\circ\text{C}$	
Gain Error		8	+14	mV	Referred to 4.096 V input range
Gain Error	-0.08		+0.08	% FSR	
Gain TC^2	-0.07	± 0.02	+0.07	% FSR	$T_A = 25^\circ\text{C}$
Full-Scale Error		± 1		ppm FSR/ $^\circ\text{C}$	
Full-Scale Error	-0.1		+0.1	% FSR	
Full-Scale TC^2	-0.07	± 0.02	+0.07	% FSR	$T_A = 25^\circ\text{C}$
Full-Scale TC^2		± 2		ppm FSR/ $^\circ\text{C}$	

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments	
OUTPUT CHARACTERISTICS²						
Current Loop Compliance Voltage	0		$AV_{DD} - 2.75$	V	Chosen such that compliance is not exceeded Needs appropriate capacitor at higher inductance values; see the Driving Inductive Loads section	
Resistive Load		See the Test Conditions/ Comments column		H		
Inductive Load				H		
Settling Time 4 mA to 20 mA, Full-Scale Step		8.5		μs		250 Ω load
120 μA Step, 4 mA to 20 mA Range		1.2		μs		250 Ω load
DC PSRR			1	$\mu\text{A/V}$		
Output Impedance		130		M Ω		
DIGITAL INPUTS²						
Input High Voltage, V_{IH}	2			V	JEDEC compliant	
Input Low Voltage, V_{IL}			0.8	V		
Input Current	-1		+1	μA	Per pin	
Pin Capacitance		5		pF	Per pin	
DIGITAL OUTPUTS²						
FAULT, IFAULT, TEMP						
V_{OL} , Output Low Voltage			0.4	V	10 k Ω pull-up resistor to DVCC	
		0.6		V	At 2.5 mA	
V_{OH} , Output High Voltage	3.6			V	10 k Ω pull-up resistor to DVCC	
SDO						
V_{OL} , Output Low Voltage	0.5	0.5		V	Sinking 200 μA	
V_{OH} , Output High Voltage	$DV_{CC} - 0.5$	$DV_{CC} - 0.5$		V	Sourcing 200 μA	
High Impedance Output Capacitance		3		pF		
High Impedance Leakage Current	-1		+1	μA		
POWER REQUIREMENTS						
AV_{DD}	10.8		55	V		
DV_{CC}						
Input Voltage	2.7		5.5	V		
AI_{DD}		4.4	5.6	mA	Output unloaded, output disabled; R3, R2, R1, R0 = 0000, RSET = 0	
		5.2	6.2	mA	Output enabled	
DI_{CC}		0.3	1	mA	$V_{IH} = DV_{CC}$, $V_{IL} = \text{GND}$	
Power Dissipation		108		mW	$AV_{DD} = 24 \text{ V}$, output unloaded	

¹ Temperature range: -40°C to +105°C; typical at +25°C.

² Guaranteed by design and characterization, not production tested.

TIMING CHARACTERISTICS

$AV_{DD} = 12\text{ V}$ ($\pm 10\%$) to 55 V (maximum), $DV_{CC} = 2.7\text{ V}$ to 5.5 V , $GND = 0\text{ V}$. $R_{LOAD} = 300\ \Omega$. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 3.

Parameter ^{1,2}	Limit at T_{MIN} , T_{MAX}	Unit	Description
t_1	20	ns min	SCLK cycle time
t_2	8	ns min	SCLK high time
t_3	8	ns min	SCLK low time
t_4	5	ns min	\overline{SYNC} falling edge to SCLK falling edge setup time
t_5	10	ns min	16 th SCLK falling edge to \overline{SYNC} rising edge (on 24 th SCLK falling edge if using PEC)
t_6	5	ns min	Minimum \overline{SYNC} high time (write mode)
t_7	5	ns min	Data setup time
t_8	5	ns min	Data hold time
t_9, t_{10}	1.5	μs max	CLEAR pulse low/high activation time
t_{11}	5	ns min	Minimum \overline{SYNC} high time (read mode)
t_{12}	40	ns max	SCLK rising edge to SDO valid ($SDO\ C_L = 15\text{ pF}$)
t_{13}	10	ns min	\overline{RESET} pulse low time

¹ Guaranteed by characterization, but not production tested.

² All input signals are specified with $t_R = t_F = 5\text{ ns}$ (10% to 90% of DV_{CC}) and timed from a voltage level of 1.2 V.

Timing Diagrams

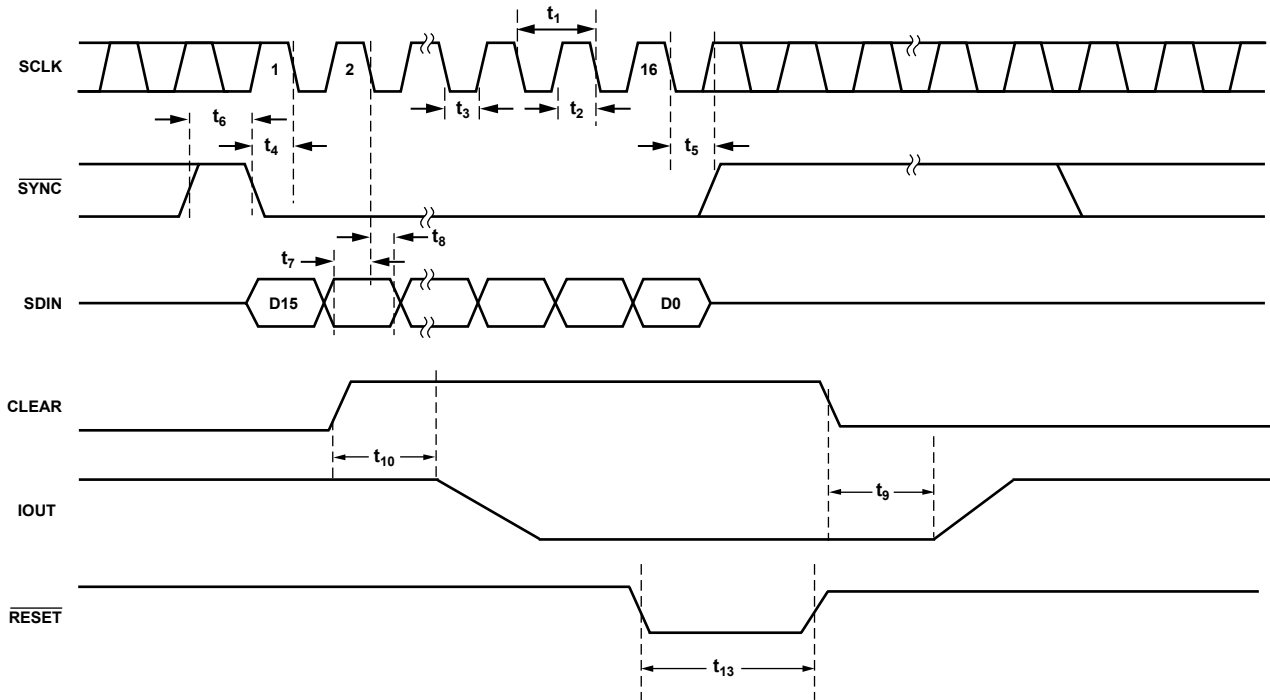


Figure 2. Write Mode Timing Diagram

08923-002

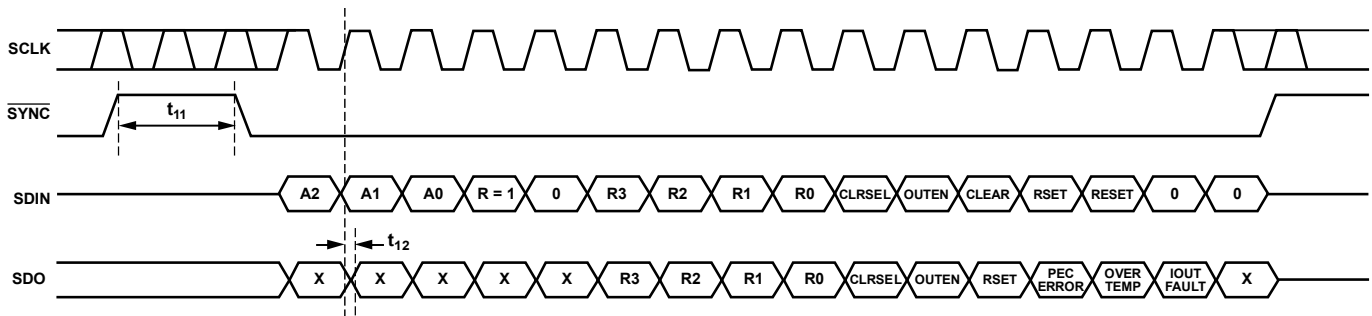


Figure 3. Readback Mode Timing Diagram

08923-003

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted. Transient currents of up to 100 mA do not cause SCR latch-up.

Table 4.

Parameter	Rating
AVDD to GND	−0.3 V to +58 V
DVCC to GND	−0.3 V to +7 V
Digital Inputs to GND	−0.3 V to $DV_{CC} + 0.3\text{ V}$, or 7 V (whichever is less)
Digital Outputs to GND	−0.3 V to $DV_{CC} + 0.3\text{ V}$, or 7 V (whichever is less)
VREF to GND	−0.3 V to +7 V
VIN to GND	−0.3 V to +7 V
IOUT to GND	−0.3 V to AV_{DD}
Operating Temperature Range	
Industrial	−40°C to +105°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature (T_J max)	125°C
32-Lead LFCSP Package	
θ_{JA} Thermal Impedance ¹	42°C/W
Lead Temperature	JEDEC industry standard
Soldering	J-STD-020

¹ Simulated data based on a JEDEC 2S2P test board with thermal vias.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

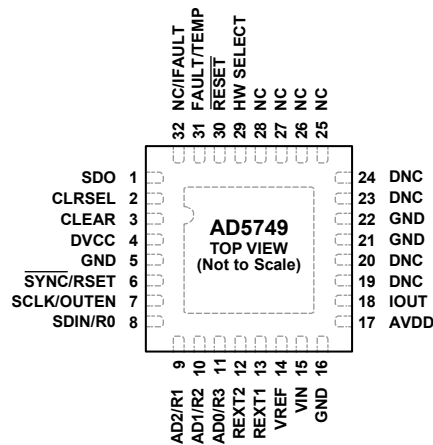
ESD CAUTION



ESD (electrostatic discharge) sensitive device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



- NOTES
1. NC = NO CONNECT. CAN BE TIED TO GND.
 2. DNC = DO NOT CONNECT.
 3. THE EXPOSED PADDLE IS TIED TO GND.

08923-004

Figure 4. Pin Configuration

Table 5. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	SDO	Serial Data Output (SDO). In software mode, this pin is used to clock data from the input shift register in readback mode. Data is clocked out on the rising edge of SCLK and is valid on the falling edge of SCLK. This pin is a CMOS output.
2	CLRSEL	In hardware or software mode, this pin selects the clear value, either zero scale or midscale. In software mode, this pin is implemented as a logic OR with the internal CLRSEL bit.
3	CLEAR	Active High Input. Asserting this pin sets the output current to zero-scale code or midscale of range selected (user selectable). CLEAR is a logic OR with the internal CLEAR bit. See the Asynchronous Clear (CLEAR) section for more details.
4	DVCC	Digital Power Supply.
5	GND	Ground Connection.
6	SYNC/RSET	Positive Edge-Sensitive Latch (SYNC). In software mode, a rising edge parallel loads the input shift register data into the AD5749 and also updates the output. Resistor Select (RSET). In hardware mode, this pin selects whether the internal or the external current sense resistor is used. If RSET = 0, the external sense resistor is chosen. If RSET = 1, the internal sense resistor is chosen.
7	SCLK/OUTEN	Serial Clock Input (SCLK). In software mode, data is clocked into the input shift register on the falling edge of SCLK. This pin operates at clock speeds up to 50 MHz. Output Enable (OUTEN). In hardware mode, this pin acts as an output enable pin.
8	SDIN/R0	Serial Data Input (SDIN). In software mode, data must be valid on the falling edge of SCLK. Range Decode Bit (R0). In hardware mode, this pin, in conjunction with R1, R2, and R3, selects the output current range setting on the part.
9	AD2/R1	Device Addressing Bit (AD2). In software mode, this pin, in conjunction with AD0 and AD1, allows up to eight devices to be addressed on one bus. Range Decode Bit (R1). In hardware mode, this pin, in conjunction with R0, R2, and R3, selects the output current range setting on the part.

Pin No.	Mnemonic	Description
10	AD1/R2	Device Addressing Bit (AD1). In software mode, this pin, in conjunction with AD0 and AD2, allows up to eight devices to be addressed on one bus. Range Decode Bit (R2). In hardware mode, this pin, in conjunction with R0, R1, and R3, selects the output current range setting on the part.
11	AD0/R3	Device Addressing Bit (AD0). In software mode, this pin, in conjunction with AD1 and AD2, allows up to eight devices to be addressed on one bus. Range Decode Bit (R3). In hardware mode, this pin, in conjunction with R0, R1, and R2, selects the output current range setting on the part.
12, 13	REXT2, REXT1	A 15 k Ω external current setting resistor can be connected between the REXT1 and REXT2 pins to improve the IOUT temperature drift performance.
14	VREF	Buffered Reference Input.
15	VIN	Buffered Analog Input (0 V to 4.096 V).
16	GND	Ground Connection.
17	AVDD	Positive Analog Supply.
18	IOUT	Current Output.
19, 20, 23, 24	DNC	Do not connect to these pins.
21, 22	GND	Ground Connection.
25, 26, 27, 28	NC	No Connect. Can be tied to GND.
29	HW SELECT	This part is used to configure the part to hardware or software mode. HW SELECT = 0 selects software control. HW SELECT = 1 selects hardware control.
30	<u>RESET</u>	In software mode, this pin resets the part to its power-on state. Active low. In hardware mode, there is no reset. If using the part in hardware mode, the <u>RESET</u> pin should be tied high.
31	FAULT/TEMP	Fault Alert (FAULT). In software mode, this pin acts as a general fault alert pin. It is asserted low when an open-circuit, overtemperature error, or PEC interface error is detected. This pin is an open-drain output and must be connected to a pull-up resistor. Overtemperature Fault (TEMP). In hardware mode, this pin acts as an overtemperature fault pin. It is asserted low when an overtemperature error is detected. This pin is an open-drain output and must be connected to a pull-up resistor.
32	NC/IFault	No Connect (NC). In software mode, this pin is a no connect. Instead, tie this pin to GND. Open-Circuit Fault Alert (IFault). In hardware mode, this pin acts as an open-circuit fault alert pin. It is asserted low when an open-circuit error is detected. This pin is an open-drain output and must be connected to a pull-up resistor.
33 (EPAD)	EPAD	The exposed paddle is tied to GND.

TYPICAL PERFORMANCE CHARACTERISTICS

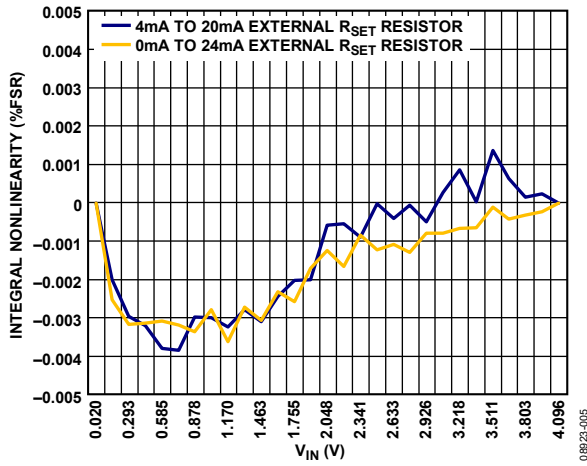


Figure 5. Integral Nonlinearity Error vs. V_{IN} , External R_{SET} Resistor

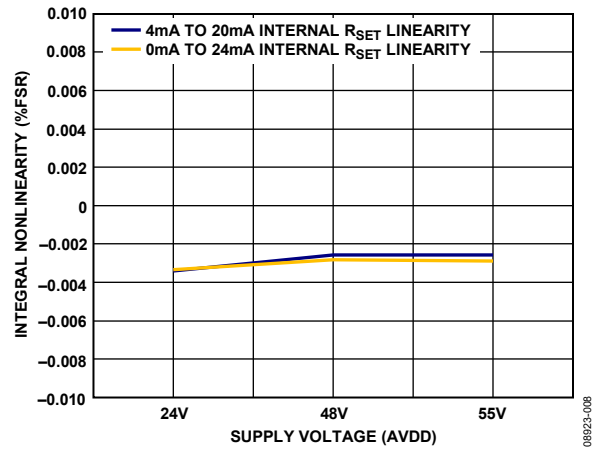


Figure 8. Integral Nonlinearity Current Mode, Internal R_{SET} Sense Resistor

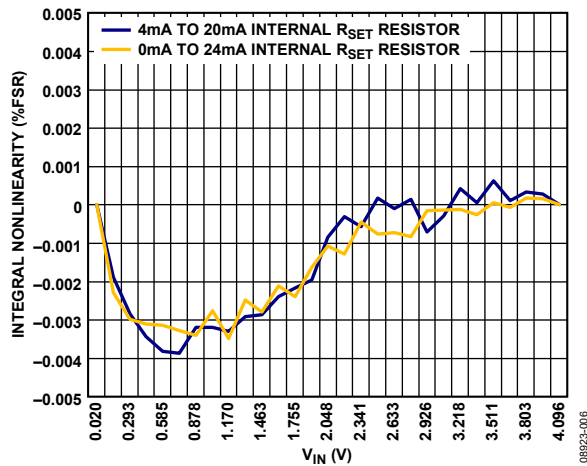


Figure 6. Integral Nonlinearity Error vs. V_{IN} , Internal R_{SET} Resistor

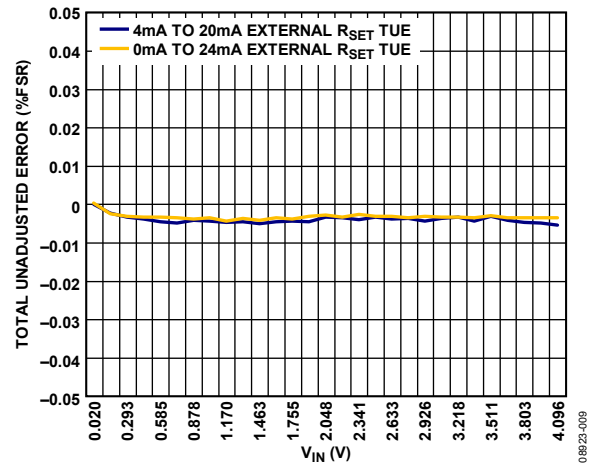


Figure 9. Total Unadjusted Error vs. V_{IN} , External R_{SET} Resistor

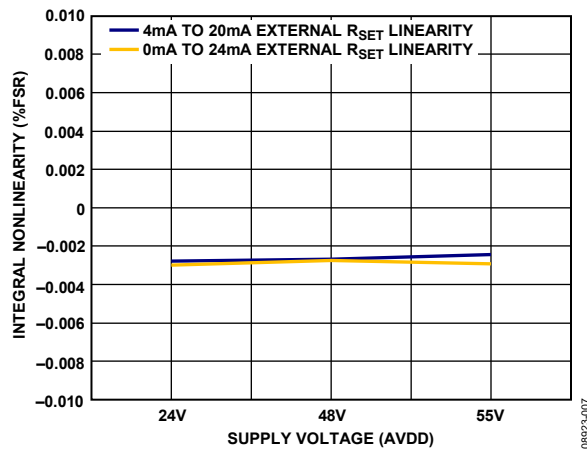


Figure 7. Integral Nonlinearity Current Mode, External R_{SET} Sense Resistor

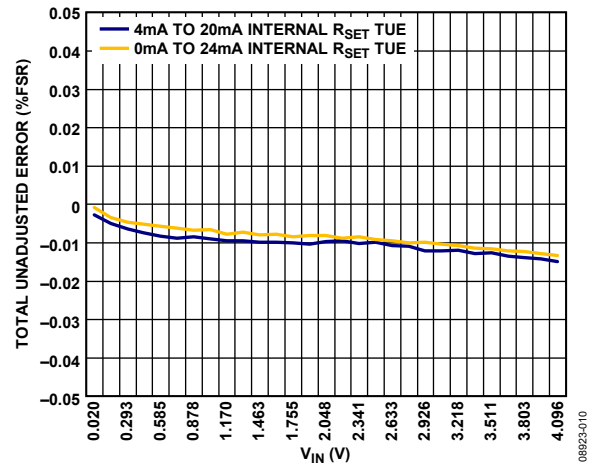


Figure 10. Total Unadjusted Error vs. V_{IN} , Internal R_{SET} Resistor

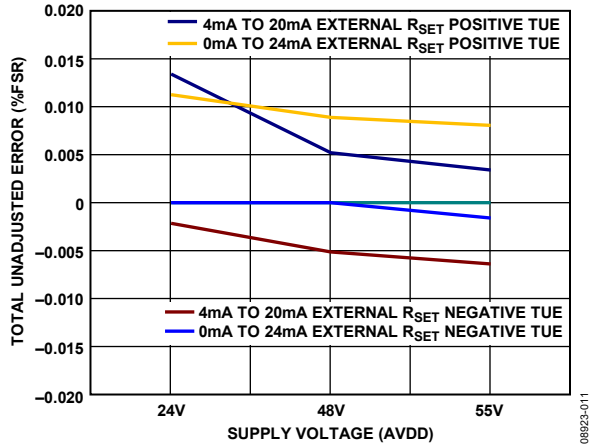


Figure 11. Total Unadjusted Error Current Mode, External R_{SET} Sense Resistor

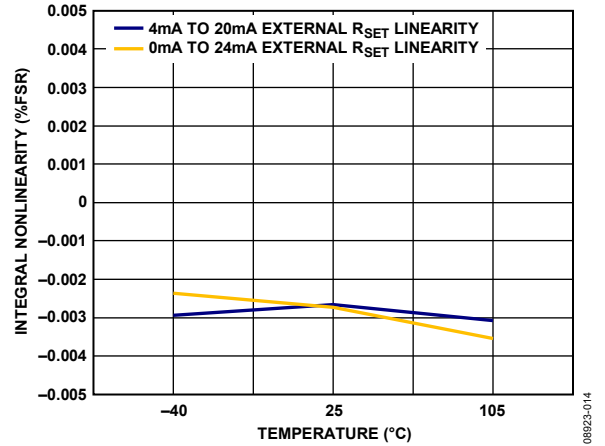


Figure 14. Integral Nonlinearity Error vs. Temperature, External R_{SET} Sense Resistor

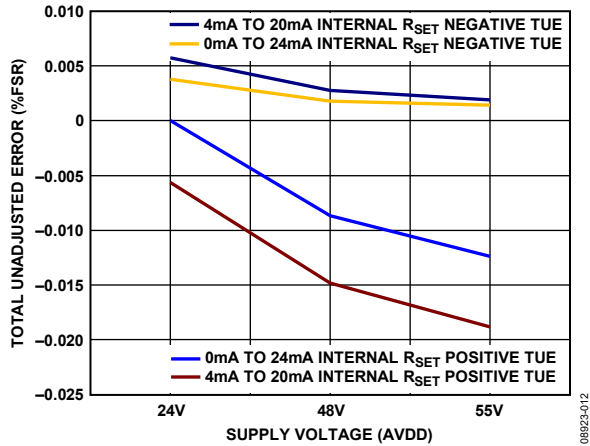


Figure 12. Total Unadjusted Error Current Mode, Internal R_{SET} Sense Resistor

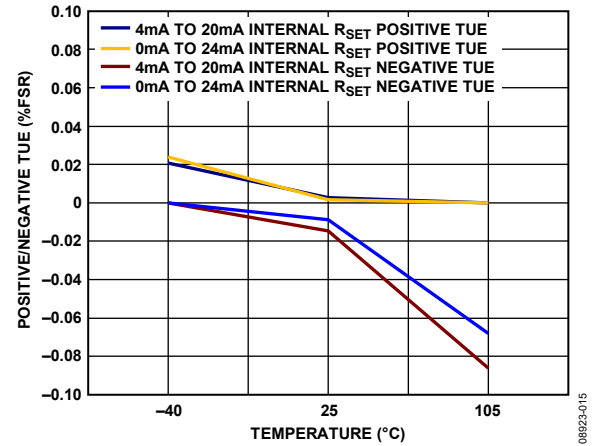


Figure 15. Total Unadjusted Error vs. Temperature, Internal R_{SET} Sense Resistor

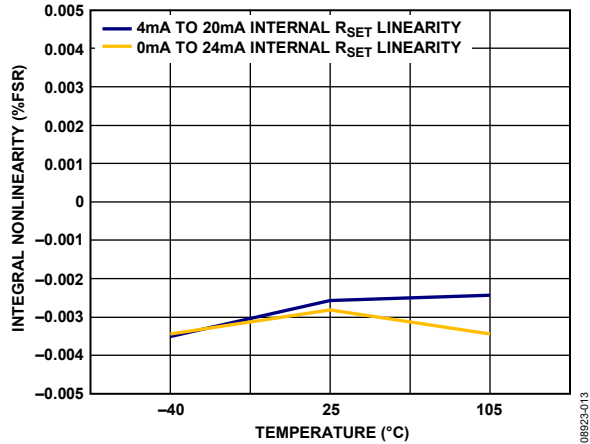


Figure 13. Integral Nonlinearity Error vs. Temperature, Internal R_{SET} Sense Resistor

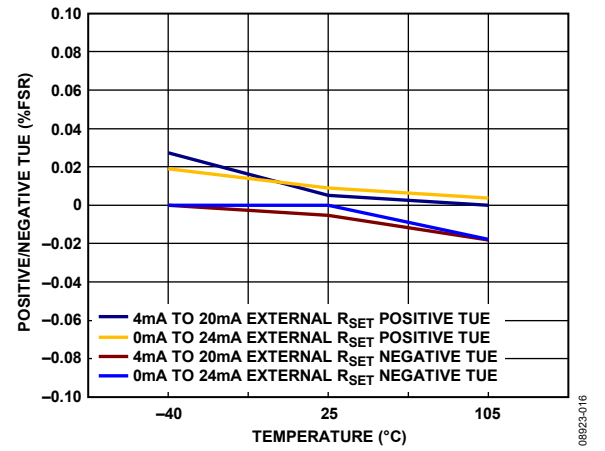


Figure 16. Total Unadjusted Error vs. Temperature, External R_{SET} Sense Resistor

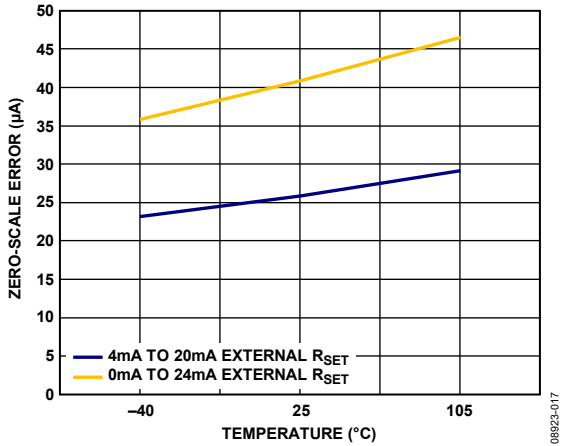


Figure 17. Zero-Scale Error vs. Temperature, External R_{SET} Sense Resistor

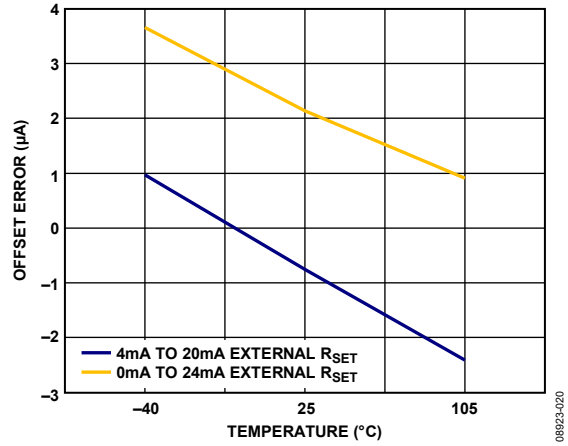


Figure 20. Offset Error vs. Temperature, External R_{SET} Sense Resistor

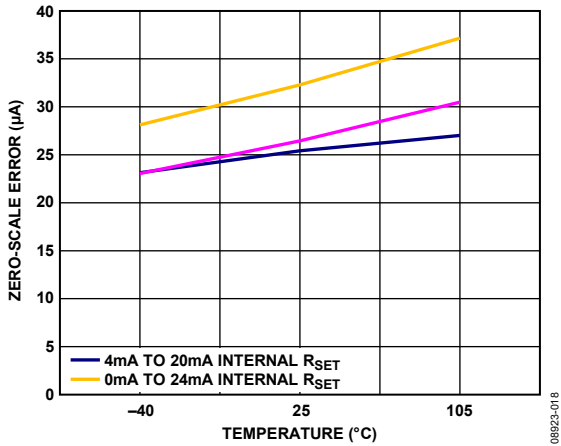


Figure 18. Zero-Scale Error vs. Temperature, Internal R_{SET} Sense Resistor

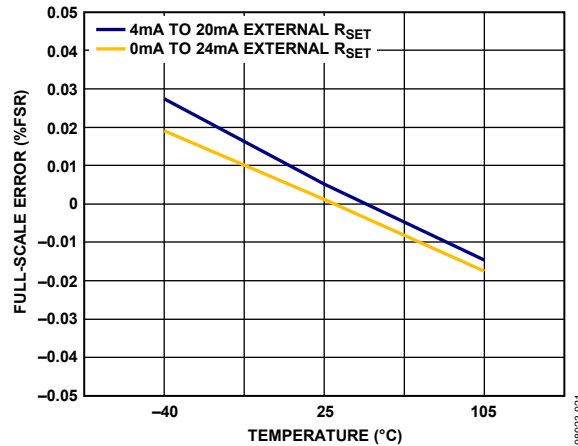


Figure 21. Full-Scale Error vs. Temperature, External R_{SET} Sense Resistor

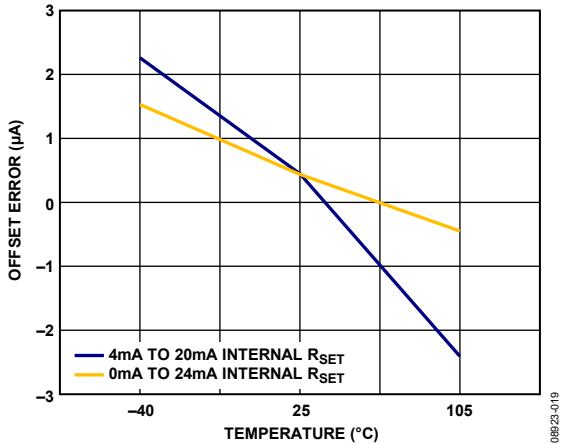


Figure 19. Offset Error vs. Temperature, Internal R_{SET} Sense Resistor

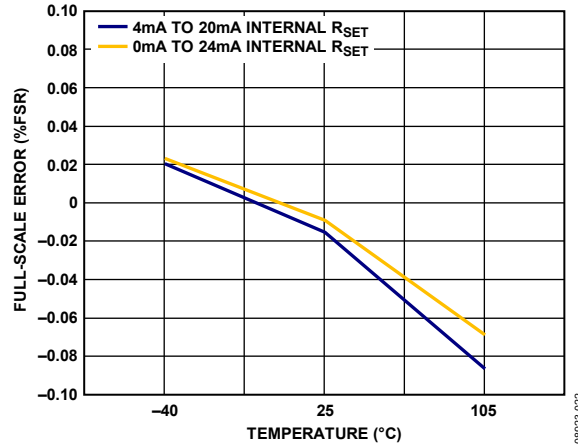


Figure 22. Full-Scale Error vs. Temperature, Internal R_{SET} Sense Resistor

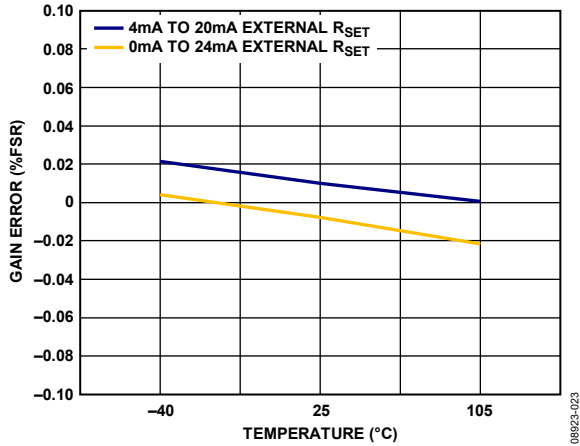


Figure 23. Gain Error vs. Temperature, External RSET Sense Resistor

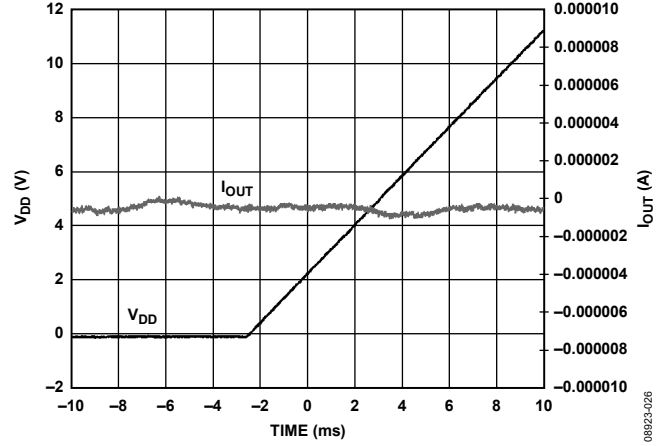


Figure 26. Output Current vs. Time on VDD Power-Up

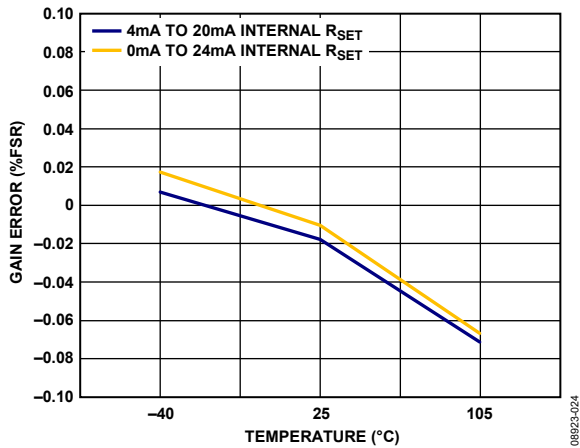


Figure 24. Gain Error vs. Temperature, Internal RSET Sense Resistor

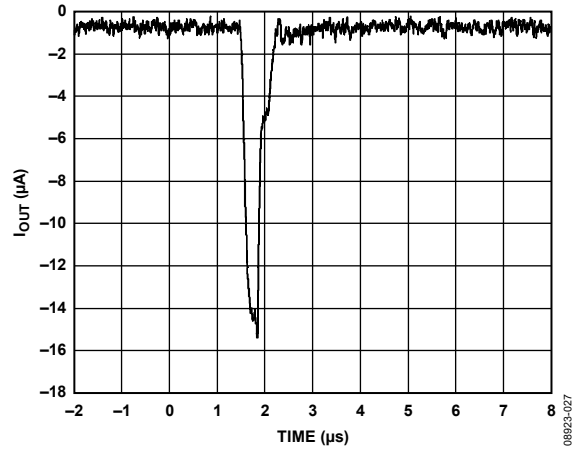


Figure 27. Output Current vs. Time on Output Enable, 0 mA to 24 mA Range

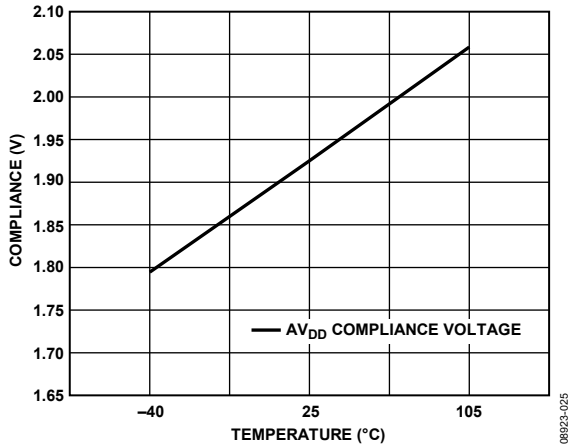


Figure 25. Output Compliance vs. Temperature Tested When IOUT = 10.8 mA, 0 mA to 24 mA Range Selected

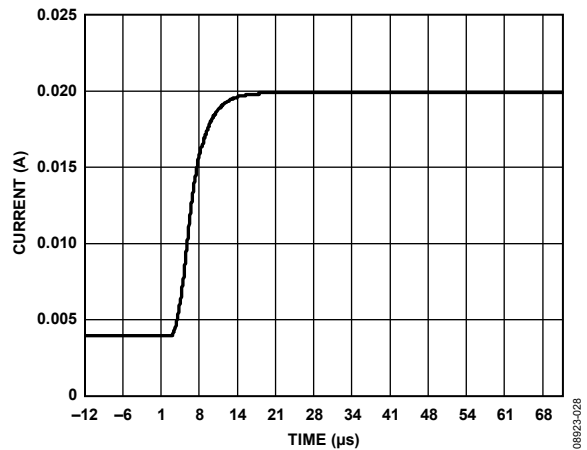


Figure 28. 4 mA to 20 mA Output Current Step

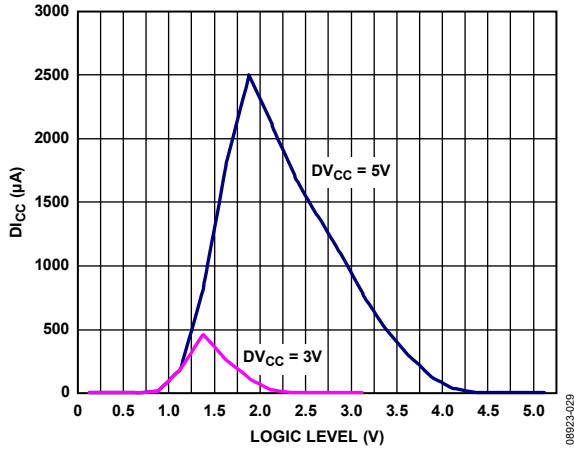


Figure 29. D_{ICC} vs. Logic Input Voltage

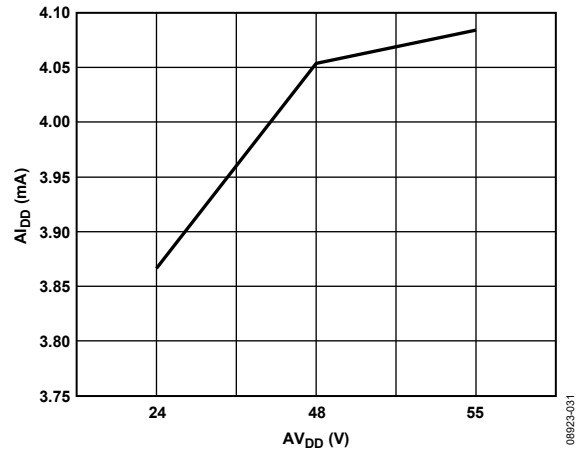


Figure 30. A_{IDD} vs. AV_{DD} , $I_{OUT} = 0 mA$

TERMINOLOGY

Total Unadjusted Error (TUE)

TUE is a measure of the output error taking all the various errors into account: INL error, offset error, gain error, and output drift over supplies, temperature, and time. TUE is expressed as a percentage of full-scale range (% FSR).

Relative Accuracy or Integral Nonlinearity (INL)

INL is a measure of the maximum deviation, in % FSR, from a straight line passing through the endpoints of the output driver transfer function. A typical INL vs. input voltage plot is shown in Figure 5.

Full-Scale Error

Full-scale error is the deviation of the actual full-scale analog output from the ideal full-scale output. Full-scale error is expressed as a percentage of full-scale range (% FSR).

Full-Scale TC

Full-scale TC is a measure of the change in the full-scale error with a change in temperature. It is expressed in ppm FSR/°C.

Gain Error

Gain error is a measure of the span error of the output. It is the deviation in slope of the output transfer characteristic from the ideal expressed in % FSR. A plot of gain error vs. temperature is shown in Figure 23.

Gain Error TC

Gain error TC is a measure of the change in gain error with changes in temperature. Gain error TC is expressed in ppm FSR/°C.

Zero-Scale Error

Zero-scale error is the deviation of the actual zero-scale analog output from the ideal zero-scale output. Zero-scale error is expressed in millivolts (mV).

Zero-Scale TC

Zero-scale TC is a measure of the change in zero-scale error with a change in temperature. Zero-scale error TC is expressed in ppm FSR/°C.

Offset Error

Offset error is a measurement of the difference between the actual VOUT and the ideal VOUT expressed in millivolts (mV) in the linear region of the transfer function. It can be negative or positive.

Output Voltage Settling Time

Output voltage settling time is the amount of time it takes for the output to settle to a specified level for a half-scale input change.

Slew Rate

The slew rate of a device is a limitation in the rate of change of the output voltage. The output slewing speed is usually limited by the slew rate of the amplifier used at its output. Slew rate is measured from 10% to 90% of the output signal and is expressed in V/μs.

Current Loop Voltage Compliance

Current loop voltage compliance is the maximum voltage at the IOUT pin for which the output current is equal to the programmed value.

Power-On Glitch Energy

Power-on glitch energy is the impulse injected into the analog output when the AD5749 is powered on. It is specified as the area of the glitch in nV-sec.

Power Supply Rejection Ratio (PSRR)

PSRR indicates how the output is affected by changes in the power supply voltage.

THEORY OF OPERATION

The **AD5749** is a single-channel, low cost, precision, current output driver with hardware or software programmable output ranges. The software ranges are configured via an SPI-/MICROWIRE-compatible serial interface. The hardware ranges are programmed using the range pins (R0 to R3). The analog input to the **AD5749** is provided from a low voltage, single-supply DAC (0 V to 4.096 V), which is internally conditioned to provide the desired output current range.

The output current range is programmable across two ranges: 0 mA to 24 mA, or 4 mA to 20 mA. An overrange of 2% is available on the 0 mA to 24 mA and 4 mA to 20 mA current ranges. The output range is selected by programming the R3 to R0 bits in the control register (see Table 7 and Table 8).

Figure 31 and Figure 32 show a typical configuration of **AD5749** in software mode and in hardware mode, respectively, in an output module system. The HW SELECT pin chooses whether the part is configured in software or hardware mode. The analog input to the **AD5749** is provided from a low voltage, single-supply DAC such as the **AD5060** and **AD5066** or **AD5660** and **AD5668**, which can provide an output range of 0 V to 4.096 V. The supply and reference for the DAC, as well as the reference for the **AD5749**, can be supplied from a reference such as the **ADR392**. The **AD5749** can operate with a single supply up to 55 V.

SOFTWARE MODE

The software-selectable output ranges are 0 mA to 24 mA, or 4 mA to 20 mA.

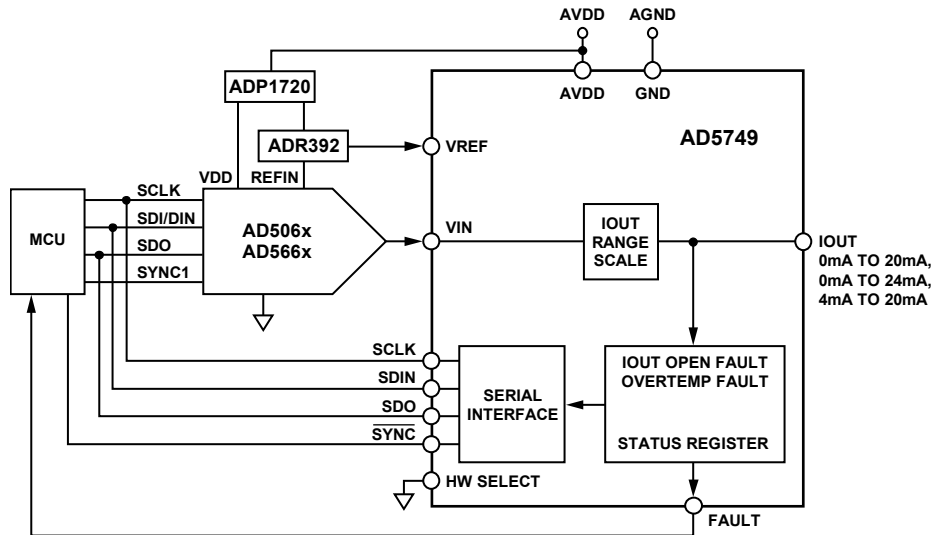


Figure 31. Typical System Configuration in Software Mode (Pull-Up Resistors Not Shown for Open-Drain Outputs)

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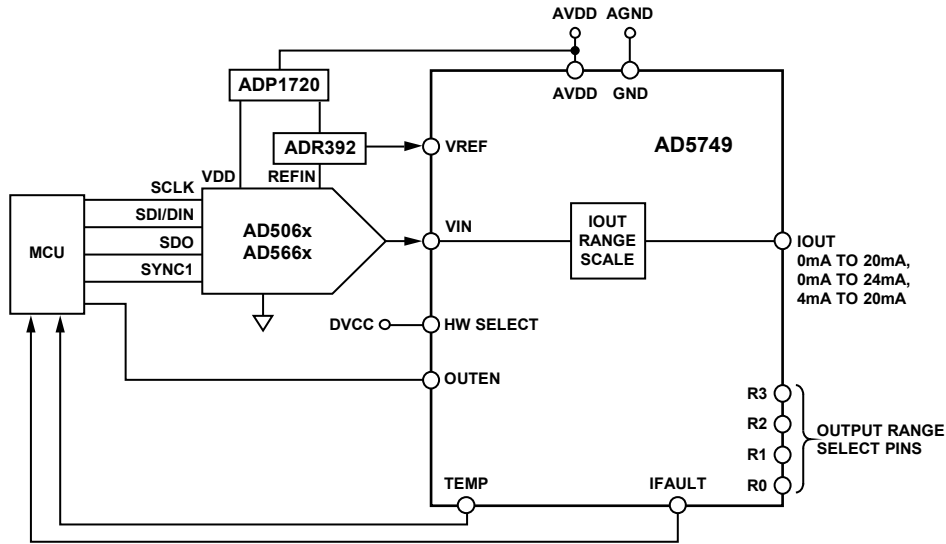


Figure 32. Typical System Configuration in Hardware Mode Using Internal DAC Reference (Pull-Up Resistors Not Shown for Open-Drain Outputs)

Table 6. Suggested Parts for Use with the AD5749

DAC	Reference	Power	Resolution/Accuracy	Description
AD5660	Internal	ADP1720 ¹	16-bit/12-bit	Mid-end system, single channel, internal reference
AD5664R	Internal	N/A	16-bit/12-bit	Mid-end system, quad channel, internal reference
AD5668	Internal	N/A	16-bit/12-bit	Mid-end system, octal channel, internal reference
AD5060	ADR434	ADP1720	16-bit/16-bit	High-end system, single channel, external reference
AD5064/AD5066	ADR434	N/A	16-bit/16-bit	High-end system, quad channel, external reference
AD5662	ADR392 ²	ADR392 ²	16-bit/12-bit	Mid-end system, single channel, external reference
AD5664	ADR392 ²	N/A	16-bit/12-bit	Mid-end system, quad channel, external reference

¹ ADP1720 input range up to 28 V.

² ADR392 input range up to 15 V.

CURRENT OUTPUT ARCHITECTURE

The voltage input from the analog input VIN core (0 V to 4.096 V) is converted to a current (see Figure 33), which is then mirrored to the supply rail so that the application simply sees a current source output with respect to an internal reference voltage. The reference is used to provide internal offsets for range and gain scaling. The selectable output range is programmable through the digital interface (software mode) or via the range pins (R0 to R3) (hardware mode).

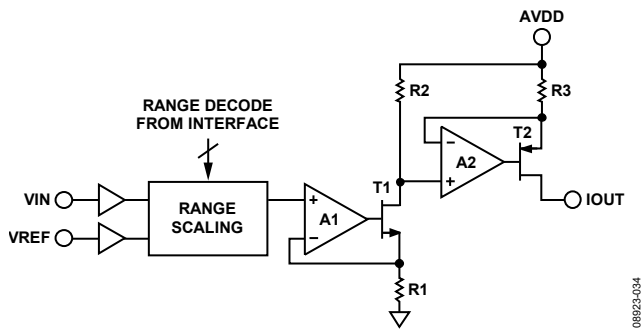


Figure 33. Current Output Configuration

DRIVING INDUCTIVE LOADS

When driving inductive or poorly defined loads, connect a 0.01 μF capacitor between IOUT and GND. This ensures stability with loads beyond 50 mH. There is no maximum capacitance limit. The capacitive component of the load may cause slower settling.

POWER-ON STATE OF THE AD5749

On power-up, the AD5749 senses whether hardware or software mode is loaded and sets the power-up conditions accordingly.

In software SPI mode, the output powers up in the tristate condition (0 mA).

To put the part into normal operation, the user must set the OUTEN bit in the control register to enable the output and, in the same write, set the output range configuration using the R3 to R0 range bits. If the CLEAR pin is still high (active) during this write, the part automatically clears to its normal clear state as defined by the programmed range and by the CLRSEL pin or the CLRSEL bit (see the Asynchronous Clear (CLEAR) section for more details). The CLEAR pin must be taken low to operate the part in normal mode.

The CLEAR pin is typically driven directly from a microcontroller. In cases where the power supply for the AD5749 supply is independent of the microcontroller power supply, the user can connect a weak pull-up resistor to DVCC or a pull-down resistor to ground to ensure that the correct power-up condition is achieved independent of the microcontroller. A 10 k Ω pull-up/pull-down resistor on the CLEAR pin should be sufficient for most applications.

If hardware mode is selected, the part powers up to the conditions defined by the R3 to R0 range bits and the status of the OUTEN or CLEAR pin. It is recommended to keep the output disabled when powering up the part in hardware mode.

DEFAULT REGISTERS AT POWER-ON

The AD5749 power-on-reset circuit ensures that all registers are loaded with zero code.

In software SPI mode, the part powers up with the output disabled (OUTEN bit = 0). The user must set the OUTEN bit in the control register to enable the output and, in the same write, set the output range configuration using the R3 to R0 bits.

If hardware mode is selected, the part powers up to the conditions defined by the R3 to R0 bits and the status of the OUTEN pin. It is recommended to keep the output disabled when powering up the part in hardware mode.

RESET FUNCTION

In software mode, the part can be reset using the $\overline{\text{RESET}}$ pin (active low) or the reset bit (reset = 1). A reset disables the output to its power-on condition. The user must write to the OUTEN bit to enable the output and, in the same write, set the output range configuration. The $\overline{\text{RESET}}$ pin is a level sensitive input; the part stays in reset mode as long as the $\overline{\text{RESET}}$ pin is low. The reset bit clears to 0 following a reset command to the control register.

In hardware mode, there is no reset. If using the part in hardware mode, the $\overline{\text{RESET}}$ pin should be tied high.

OUTEN

In software mode, the output can be enabled or disabled using the OUTEN bit in the control register. When the output is disabled, it is placed into tristate. The user must set the OUTEN bit to enable the output and simultaneously set the output range configuration.

In hardware mode, the output can be enabled or disabled using the OUTEN pin. When the output is disabled, it is placed into tristate. The user must write to the OUTEN pin to enable the output. It is recommended that the output be disabled when changing the ranges.

SOFTWARE CONTROL

Software control is enabled by connecting the HW SELECT pin to ground. In software mode, the AD5749 is controlled over a versatile 3-wire serial interface that operates at clock rates up to 50 MHz. It is compatible with SPI, QSPI[™], MICROWIRE, and DSP standards.

Input Shift Register

The input shift register is 16 bits wide. Data is loaded into the device MSB first as a 16-bit word under the control of a serial clock input, SCLK. Data is clocked in on the falling edge of SCLK. The input shift register consists of 16 control bits, as shown in Table 7. The timing diagram for this write operation is shown in Figure 2. The first three bits of the input shift register are used to set the hardware address of the AD5749 device on the printed circuit board (PCB). Up to eight devices can be addressed per board.

Bit D11, Bit D1, and Bit D0 must always be set to 0 during any write sequence.

Table 7. Input Shift Register Contents for a Write Operation—Control Register

MSB														LSB	
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
A2	A1	A0	R/W	0	R3	R2	R1	R0	CLRSEL	OUTEN	CLEAR	RSET	RESET	0	0

Table 8. Input Shift Register Descriptions for Control Register

Bit	Description					
A2, A1, A0	Used in association with the AD2, AD1, and AD0 external pins to determine which part is being addressed by the system controller.					
	A2	A1	A0	Function		
	0	0	0	Addresses part with Pin AD2 = 0, Pin AD1 = 0, Pin AD0 = 0.		
	0	0	1	Addresses part with Pin AD2 = 0, Pin AD1 = 0, Pin AD0 = 1.		
	0	1	0	Addresses part with Pin AD2 = 0, Pin AD1 = 1, Pin AD0 = 0.		
	0	1	1	Addresses part with Pin AD2 = 0, Pin AD1 = 1, Pin AD0 = 1.		
	1	0	0	Addresses part with Pin AD2 = 1, Pin AD1 = 0, Pin AD0 = 0.		
	1	0	1	Addresses part with Pin AD2 = 1, Pin AD1 = 0, Pin AD0 = 1.		
	1	1	0	Addresses part with Pin AD2 = 1, Pin AD1 = 1, Pin AD0 = 0.		
	1	1	1	Addresses part with Pin AD2 = 1, Pin AD1 = 1, Pin AD0 = 1.		
R/W	Indicates a read from or a write to the addressed register.					
R3, R2, R1, R0	Selects the output configuration in conjunction with RSET.					
	RSET	R3	R2	R1	R0	Output Configuration
	0	0	0	0	0	4 mA to 20 mA (external 15 kΩ current sense resistor).
	0	0	0	0	1	Unused command. Do not program.
	0	0	0	1	0	0 mA to 24 mA (external 15 kΩ current sense resistor).
	0	0	0	1	1	Unused command. Do not program.
	0	0	1	0	0	Unused command. Do not program.
	0	0	1	0	1	Unused command. Do not program.
	0	0	1	1	0	Unused command. Do not program.
	0	0	1	1	1	Unused command. Do not program.
	0	1	0	0	0	Unused command. Do not program.
	0	1	0	0	1	Unused command. Do not program.
	0	1	0	1	0	Unused command. Do not program.
	0	1	0	1	1	Unused command. Do not program.
	0	1	1	0	0	Unused command. Do not program.
	0	1	1	0	1	Unused command. Do not program.
	0	1	1	1	0	Unused command. Do not program.
	0	1	1	1	1	Unused command. Do not program.
	1	0	0	0	0	4 mA to 20 mA (internal current sense resistor).
	1	0	0	0	1	Unused command. Do not program.
	1	0	0	1	0	0 mA to 24 mA (internal current sense resistor).
	1	0	0	1	1	Unused command. Do not program.
	1	0	1	0	0	Unused command. Do not program.
	1	0	1	0	1	Unused command. Do not program.
	1	0	1	1	0	Unused command. Do not program.
	1	0	1	1	1	Unused command. Do not program.
	1	1	0	0	0	Unused command. Do not program.
	1	1	0	0	1	Unused command. Do not program.
	1	1	0	1	0	Unused command. Do not program.
	1	1	0	1	1	Unused command. Do not program.
	1	1	1	0	0	Unused command. Do not program.
	1	1	1	0	1	3.92 mA to 20.4 mA (internal current sense resistor).
	1	1	1	1	0	Unused command. Do not program.
	1	1	1	1	1	0 mA to 24.5 mA (internal current sense resistor).

Bit	Description	
CLRSEL	Sets clear mode to zero scale or midscale. See the Asynchronous Clear (CLEAR) section.	
	CLRSEL	Function
	0	Clear to zero-scale.
	1	Clear to midscale.
OUTEN	Output enable bit. This bit must be set to 1 to enable the output.	
CLEAR	Software clear bit; active high.	
RSET	Select internal/external current sense resistor.	
	RSET	Function
	1	Select internal current sense resistor; used with R3 to R0 bits to select range.
	0	Select external current sense resistor; used with R3 to R0 bits to select range.
RESET	Resets the part to its power-on state.	

Status Bit Read Operation

A read of the status bits can be initiated as part of a normal write operation. The read is activated by selecting the correct device address (A2, A1, A0) and then setting the $\overline{R/\overline{W}}$ bit to 1. By default, the SDO pin is disabled. After having addressed the AD5749 and setting $\overline{R/\overline{W}}$ to 1 the SDO pin is enabled and data is clocked out on the 5th rising edge of SCLK. After all the data has been clocked out on SDO, a rising edge on \overline{SYNC} disables (tristates) the SDO pin again. Status register data (see Table 9) and control register data are both available during the same read cycle. Data contained in Bit D10 to Bit D0 of the write operation are still valid and can be used to change the operating mode of the AD5749 if required.

The status bits comprise three read-only bits. They are used to notify the user of specific fault conditions that occur, such as an open circuit on the output, over-temperature error or an interface error. If any of these fault conditions occur, a hardware FAULT is also asserted low, which can be used as a hardware interrupt to the controller.

See the Detailed Description of Features section for a full explanation of fault conditions.

HARDWARE CONTROL

Hardware control is enabled by connecting the HW SELECT pin to DVCC. In this mode, the R3, R2, R1, and R0 pins, in conjunction with the RSET pin, are used to configure the output range, as per Table 8.

In hardware mode, there is no status register. The fault conditions (open circuit, and overtemperature) are available on Pin IFAULT and Pin TEMP. If any one of these fault conditions is set, a low is asserted on the specific fault pin. IFAULT and TEMP are open-drain outputs and, therefore, can be connected together to allow the user to generate one interrupt to the system controller to communicate a fault. If hardwired in this way, it is not possible to isolate which fault occurred in the system.

TRANSFER FUNCTION

The AD5749 consists of an internal signal conditioning block that maps the analog input voltage to a programmed output range. The available analog input range is 0 V to 4.096 V.

For all ranges, the AD5749 implements a straight linear mapping function, where 0 V maps to the lower end of the selected range and 4.096 V maps to the upper end of the selected range.

Table 9. Input Shift Register Contents for a Read Operation—Status Register

MSB													LSB		
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
A2	A1	A0	1	0	R3	R2	R1	R0	CLRSEL	OUTEN	RSET	PEC Error	OVER TEMP	IOUT Fault	Unused

Table 10. Status Bit Options

Bit	Description
PEC Error	This bit is set if there is an interface error detected by CRC-8 error checking. See the Detailed Description of Features section.
OVER TEMP	This bit is set if the AD5749 core temperature exceeds approximately 150°C.
IOUT Fault	This bit is set if there is an open circuit on the IOUT pin.

DETAILED DESCRIPTION OF FEATURES

OUTPUT FAULT ALERT—SOFTWARE MODE

In software mode, the AD5749 is equipped with one FAULT pin; this is an open-drain output allowing several AD5749 devices to be connected together to one pull-up resistor for global fault detection. In software mode, the FAULT pin is forced active low by any one of the following fault scenarios:

- The voltage at IOUT attempts to rise above the compliance range due to an open-loop circuit or insufficient power supply voltage. The internal circuitry that develops the fault output avoids using a comparator with window limits because this requires an actual output error before the fault output becomes active. Instead, the signal is generated when the internal amplifier in the output stage has less than approximately 1 V of remaining drive capability. Thus, the fault output activates slightly before the compliance limit is reached. Because the comparison is made within the feedback loop of the output amplifier, the output accuracy is maintained by its open-loop gain, and an output error does not occur before the fault output becomes active.
- An interface error is detected due to the packet error checking failure (PEC). See the Packet Error Checking section.
- The core temperature of the AD5749 exceeds approximately 150°C.

OUTPUT FAULT ALERT—HARDWARE MODE

In hardware mode, the AD5749 is equipped with two fault pins: IFAULT and TEMP. These are open-drain outputs allowing several AD5749 devices to be connected together to one pull-up resistor for global fault detection. In hardware control mode, these fault pins are forced active by any one of the following fault scenarios:

- An open-circuit is detected. The voltage at IOUT attempts to rise above the compliance range, due to an open-loop circuit or insufficient power supply voltage. The internal circuitry that develops the fault output avoids using a comparator with window limits because this requires an actual output error before the fault output becomes active. Instead, the signal is generated when the internal amplifier in the output stage has less than approximately 1 V of remaining drive capability. Thus, the fault output activates slightly before the compliance limit is reached. Because the comparison is made within the feedback loop of the output amplifier, the output accuracy is maintained by its open-loop gain, and an output error does not occur before the fault output becomes active. If this fault is detected, the IFAULT pin is forced low.

- The core temperature of the AD5749 exceeds approximately 150°C. If this fault is detected, the TEMP pin is forced low.

ASYNCHRONOUS CLEAR (CLEAR)

CLEAR is an active high clear that allows the output to be cleared to either zero-scale or midscale, and is user-selectable via the CLRSEL pin or the CLRSEL bit of the input shift register, as described in Table 8. (The clear select feature is a logical OR function of the CLRSEL pin and the CLRSEL bit). When the CLEAR signal is returned low, the output returns to its programmed value or to a new programmed value. A clear operation can also be performed via the clear command in the control register.

Table 11. CLRSEL Options

CLRSEL	Output Clear Value
0	Zero scale; for example: 4 mA on the 4 mA to 20 mA range 0 mA on the 0 mA to 24 mA range
1	Midscale; for example: 12 mA on the 4 mA to 20 mA range 12 mA on the 0 mA to 24 mA range

EXTERNAL CURRENT SETTING RESISTOR

Referring to Figure 1, R_{SET} is an internal sense resistor and is part of the voltage-to-current conversion circuitry. The nominal value of the internal current sense resistor is 15 k Ω . To allow for overrange capability in current mode, the user can also select the internal current sense resistor to be 14.7 k Ω , giving a nominal 2% overrange capability. This feature is available in the 0 mA to 24 mA, and 4 mA to 20 mA current ranges.

The stability of the output current value over temperature is dependent on the stability of the value of R_{SET} . As a method of improving the stability of the output current over temperature, an external low drift resistor can be connected to the REXT1 and REXT2 pins of the AD5749, which can be used instead of the internal resistor. The external resistor is selected via the input shift register. If the external resistor option is not used, the REXT1 and REXT2 pins should be left floating.

PROGRAMMABLE OVERRANGE MODES

The AD5749 contains an overrange mode. The overranges are selected by configuring the R3, R2, R1, and R0 bits (or pins) accordingly.

The overranges are typically 2%. For these ranges, the analog input remains the same (0 V to 4.096 V).

PACKET ERROR CHECKING

To verify that data has been received correctly in noisy environments, the AD5749 offers the option of error checking based on an 8-bit (CRC-8) cyclic redundancy check. The device controlling the AD5749 should generate an 8-bit frame check sequence using the following polynomial:

$$C(x) = x^8 + x_2 + x_1 + 1$$

This is added to the end of the data-word, and 24 data bits are sent to the AD5749 before taking SYNC high. If the AD5749 receives a 24-bit data frame, it performs the error check when SYNC goes high. If the check is valid, then the data is written to the selected register. If the error check fails, the FAULT pin goes low and Bit D3 of the status register is set. After reading this register, this error flag is cleared automatically and the FAULT pin goes high again.

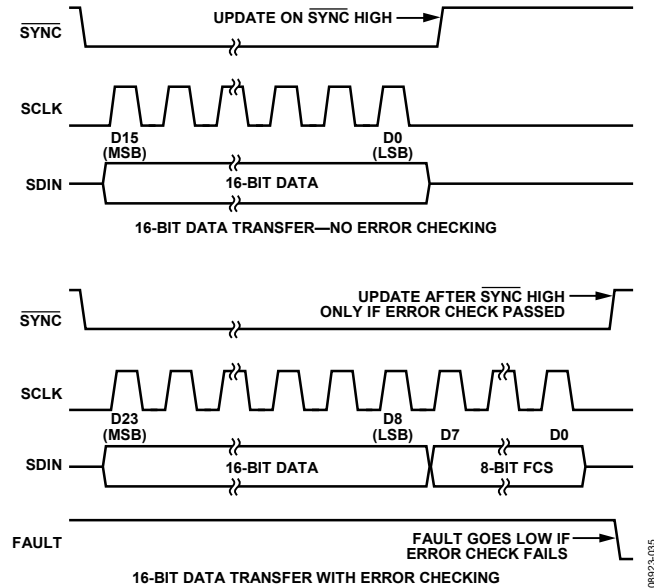


Figure 34. PEC Error Checking Timing

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APPLICATIONS INFORMATION

TRANSIENT VOLTAGE PROTECTION

The AD5749 contains ESD protection diodes that prevent damage from normal handling. The industrial control environment can, however, subject I/O circuits to much higher transients. To protect the AD5749 from excessively high voltage transients, external power diodes and a surge current limiting resistor may be required, as shown in Figure 35. The constraint on the resistor value is that during normal operation the output level at IOOUT must remain within its voltage compliance limit of $AV_{DD} - 2.75$ V and the two protection diodes and resistor must have appropriate power ratings. Further protection can be added with transient voltage suppressors if needed.

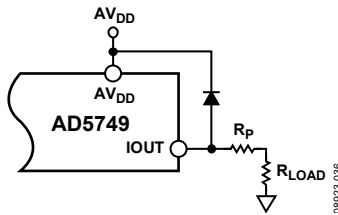


Figure 35. Output Transient Voltage Protection

THERMAL CONSIDERATIONS

It is important to understand the effects of power dissipation on the package and how it affects junction temperature. The internal junction temperature should not exceed 125°C. The AD5749 is packaged in a 32-lead, 5 mm × 5 mm LFCSP package. The thermal impedance, θ_{JA} , is 42°C/W. It is important that the devices not be operated under conditions that cause the junction temperature to exceed its limit. Worst-case conditions occur when the AD5749 is operated from the maximum AV_{DD} (55 V) and driving the maximum current (24 mA) directly to ground. The quiescent current of the AD5749 should also be taken into account, nominally ~4 mA.

The calculations in Table 12 estimate maximum power dissipation under these worst-case conditions, and determine maximum ambient temperature based on this. These figures assume that proper layout and grounding techniques are followed to minimize power dissipation, as outlined in the Layout Guidelines section.

Table 12. Thermal and Supply Considerations

Considerations	32-Lead LFCSP Package
Maximum allowed power dissipation when operating at an ambient temperature of 85°C	$\frac{T_{JMAX} - T_A}{\theta_{JA}} = \frac{125 - 85}{42} = 0.95$ W
Maximum allowed ambient temperature when operating from a supply of 55 V and driving 24 mA directly to ground (include 4 mA for internal AD5749 current)	$T_{JMAX} - (P_D \times \theta_{JA}) = 125 - ((55 \times 0.028) \times 42) = 60.3^\circ\text{C}$
Maximum allowed supply voltage when operating at an ambient temperature of 85°C and driving 24 mA directly to ground	$\frac{T_{JMAX} - T_A}{AI_{DD} \times \theta_{JA}} = \frac{125 - 85}{(0.028 \times 42)} = 34$ V

LAYOUT GUIDELINES

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The PCB on which the AD5749 is mounted should be designed so that the AD5749 lies on the analog plane.

The AD5749 should have ample supply bypassing of 10 μF in parallel with 0.1 μF on each supply, located as close to the package as possible, ideally right up against the device. The 10 μF capacitors are the tantalum bead type. The 0.1 μF capacitor should have low effective series resistance (ESR) and low effective series inductance (ESI) such as the common ceramic types, which provide a low impedance path to ground at high frequencies to handle transient currents due to internal logic switching.

In systems where there are many devices on one board, it is often useful to provide some heat sinking capability to allow the power to dissipate easily.

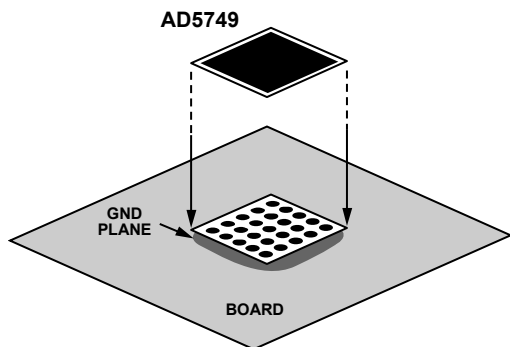


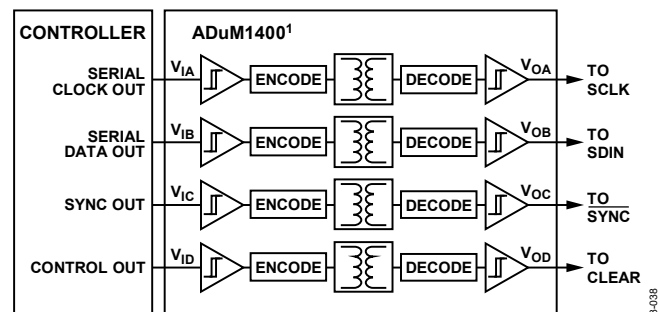
Figure 36. Paddle Connection to Board

The AD5749 has an exposed paddle beneath the device. Connect this paddle to the GND of the AD5749. For optimum performance, special considerations should be used to design the motherboard and to mount the package. For enhanced thermal, electrical, and board level performance, the exposed paddle on the bottom of the package should be soldered to the

corresponding thermal land paddle on the PCB (GND). Thermal vias should be designed into the PCB land paddle area to further improve heat dissipation.

GALVANICALLY ISOLATED INTERFACE

In many process control applications, it is necessary to provide an isolation barrier between the controller and the unit being controlled to protect and isolate the controlling circuitry from any hazardous common-mode voltages that may occur. The iCoupler® family of products from Analog Devices, Inc., provides voltage isolation in excess of 5.0 kV. The serial loading structure of the AD5749 makes it ideal for isolated interfaces because the number of interface lines is kept to a minimum. Figure 37 shows a 4-channel isolated interface to the AD5749 using an ADuM1400. For further information, visit <http://www.analog.com/icouplers>.



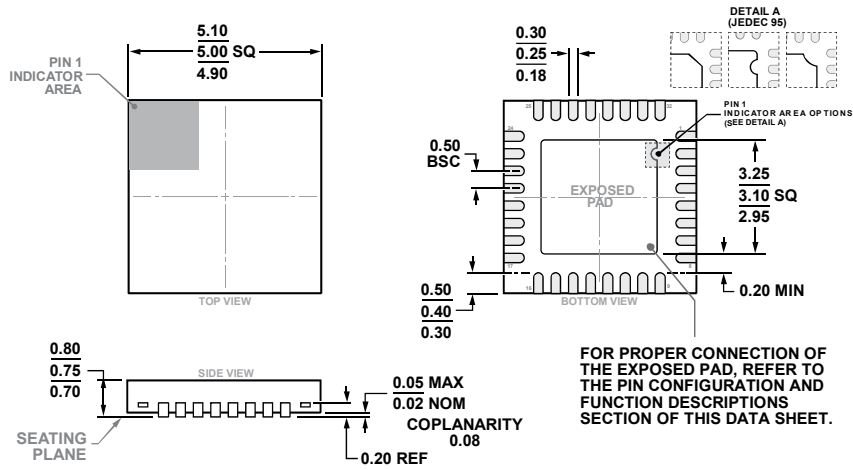
¹ADDITIONAL PINS OMITTED FOR CLARITY.

Figure 37. Isolated Interface

MICROPROCESSOR INTERFACING

Microprocessor interfacing to the AD5749 is via a serial bus that uses a protocol compatible with microcontrollers and DSP processors. The communication channel is a 3-wire (minimum) interface consisting of a clock signal, a data signal, and a SYNC signal. The AD5749 requires a 16-bit data-word with data valid on the falling edge of SCLK.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-220-WHHD

Figure 38. 32-Lead Lead Frame Chip Scale Package [LFCSP]
5 mm x 5 mm Body and 0.75 mm Package Height
(CP-32-7)
Dimensions shown in millimeters

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option
AD5749ACPZ	-40°C to +105°C	32-Lead LFCSP	CP-32-7
AD5749ACPZ-RL7	-40°C to +105°C	32-Lead LFCSP	CP-32-7

¹ Z = RoHS Compliant Part.

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